

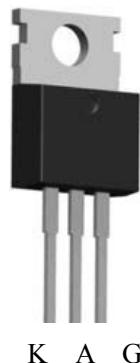
YAREN STANDARD 12A SCRs

General Description

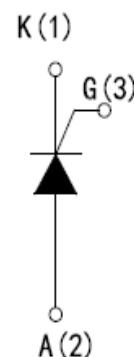
Glass passivated thyristors in a plastic envelope ,Intended for use applications requiring high bidirectional blocking voltage capability and high thermal cycling performance.Typical applications include motor control ,industrial and domestic lighting, heating and static switching.

Features

- IT(AV)=12A
- IGT≤15mA
- VTM≤1. 6V



To-220 Top View



Schematic Diagram

VDRM = 600 V

IT(AV)= 12A

IGT≤15mA

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
TYN612	TYN612	T0-220CE	-	-	-

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter/ Conditions	Value	Unit
VDRM/VRRM	Repetitive peak off-state Voltages	600	V
IT(AV)	Average on-state current (half sine wave;Tmb≤109 °C)	12	A
IT(RMS)	RMS on-state current (all conduction angles)	20	A
ITSM	Non-repetitive peak on-state current(half sine wave;Tj=25 °C t=10ms)	200	A
	Non-repetitive peak on-state current(half sine wave;Tj=25 °C t=8.3ms)	220	A
I ² T	I ² T for fusing (t=10ms)	200	A ² s
Dit/dt	Repetitive rate of rise of on-state current after triggering (I _{TM} =20A;IG=50mA;Dig/dt=50mA/us)	200	A/us
IGM	Peak gate current	5	A
VGM	Peak gate voltage	5	V
PGM	Peak gate power	20	W
P G(AV)	Average gate power (over any 20 ms period)	0.5	W
TJ	Operating junction temperature	-55 To 150	°C

Thermal Resistances

Symbol	Parameter	Value	Unit
R _{th(j-c)}	Junction to case(DC)	1.1	°C/W
R _{th(j-a)}	Junction-to-Ambient(DC)	60	°C/W

Electrical Characteristics (TA=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
IGT	Gate trigger current	VD=12V IT=0.1V		4	15	mA
VGT	Gate trigger Voltage	VD=12V IT=0.1V		0.6	1.5	V
		V D=VDRM(MAX);IT =0.1A;TJ=125°C	0.25	0.4		V
VT	On-state voltage	V IT =23A		1.4	1.75	V
IL	Latching current	VD=12V IT=0.1V		25	80	mA
IH	Holding current	VD=12V IT=0.1V		15	60	mA
ID/IR	Off-state leakage current	V D=VDRM(MAX);VR=VRRM(MAX);TJ=125°C		0.2	1.0	mA

Dynamic Characteristics

DVD/DT	Critical rate of rise or off-state voltage	VDM=67%VDRM(MAX) ; TJ=125 °C; (Gate open circuit)	200	300		V/us
		RGK=100Ω	200	1000		V/us
TGT	Gate controlled turn-on time	ITM=40A;VD=VDRM(MAX);IG=0.1 A, Dig/dt=5A/us		2		us
TG	Circuit commutated turn-off time	VD=67%VDRM(MAX);TJ=125 °C ITM=20A;VR=25V;Ditm/dt=30A/us dvd/dt=50V/us;Rgk=100 Ω		70		us

Characteristics Curve:

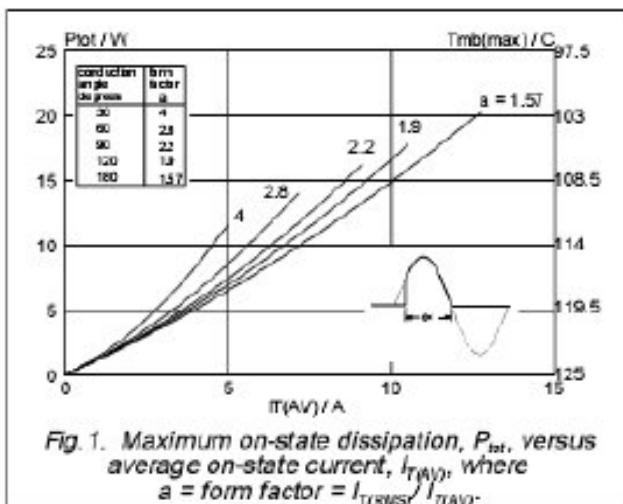


Fig. 1. Maximum on-state dissipation, P_d , versus average on-state current, $I_{T(AV)}$, where a = form factor = $I_{T(RMS)} / I_{T(AV)}$.

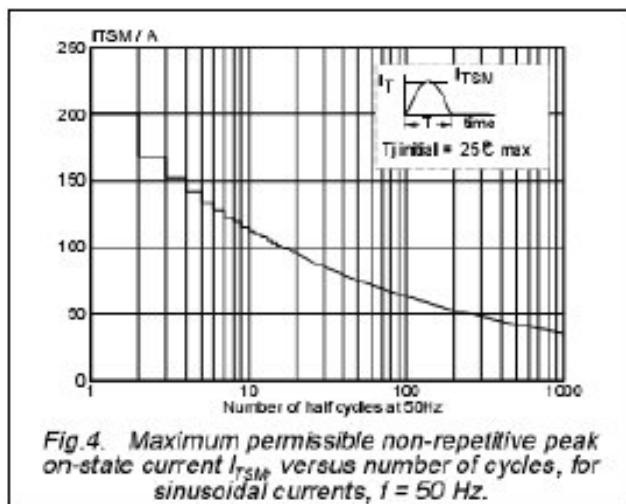


Fig. 4. Maximum permissible non-repetitive peak on-state current I_{TSM} versus number of cycles, for sinusoidal currents, $f = 50$ Hz.

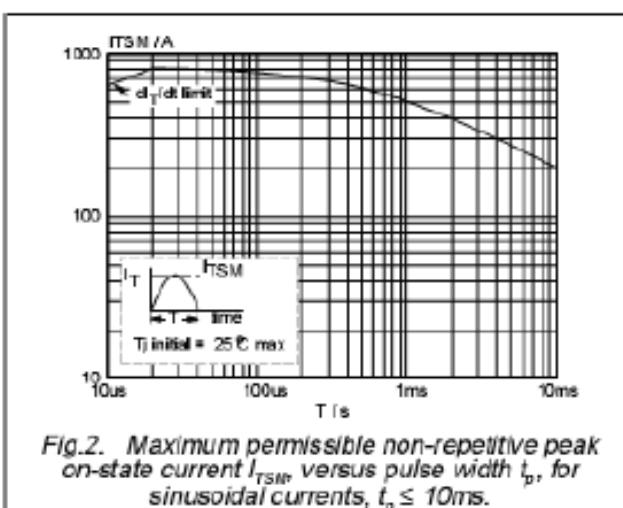


Fig. 2. Maximum permissible non-repetitive peak on-state current I_{TSM} versus pulse width t_p , for sinusoidal currents, $t_p \leq 10\text{ms}$.

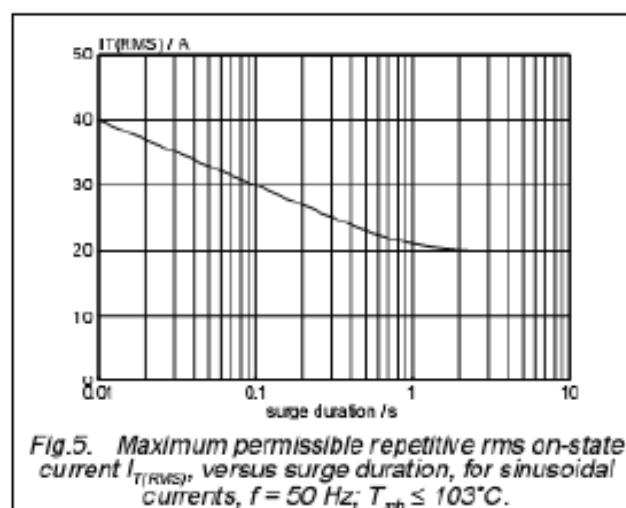


Fig. 5. Maximum permissible repetitive rms on-state current I_{TRMS} , versus surge duration, for sinusoidal currents, $f = 50$ Hz; $T_{mb} \leq 103^\circ\text{C}$.

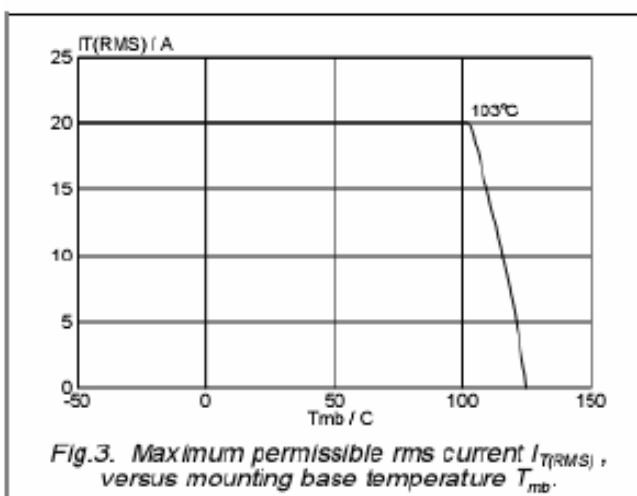


Fig. 3. Maximum permissible rms current I_{TRMS} , versus mounting base temperature T_{mb} .

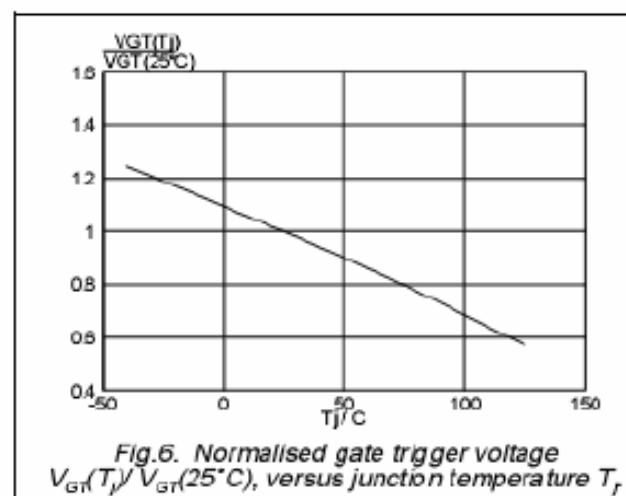


Fig. 6. Normalised gate trigger voltage $V_{GT}(T_f) / V_{GT}(25^\circ\text{C})$, versus junction temperature T_f .

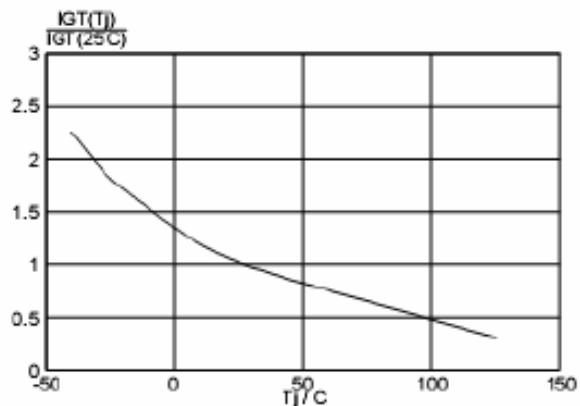


Fig. 7. Normalised gate trigger current $I_{GT}(T_j)/I_{GT}(25^\circ C)$, versus junction temperature T_j

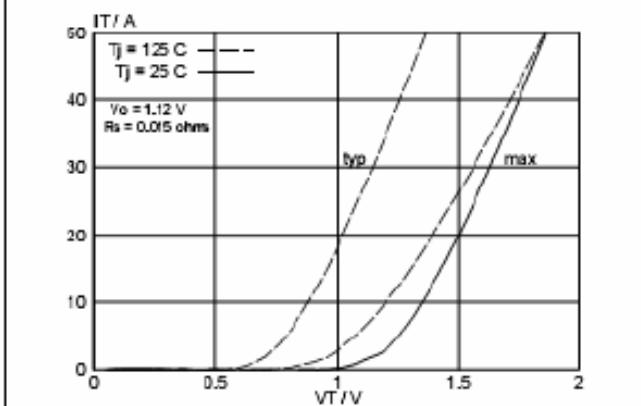


Fig. 10. Typical and maximum on-state characteristic.

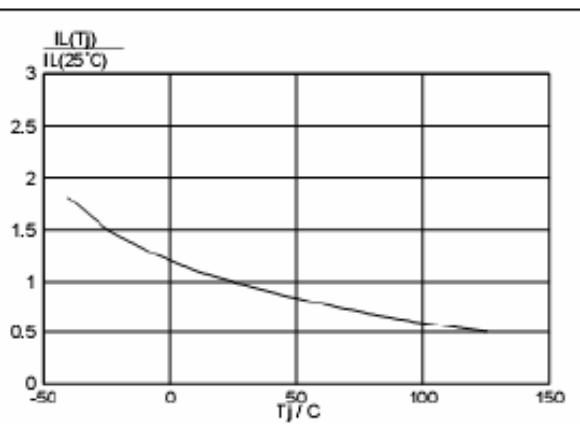


Fig. 8. Normalised latching current $I_L(T_j)/I_L(25^\circ C)$, versus junction temperature T_j

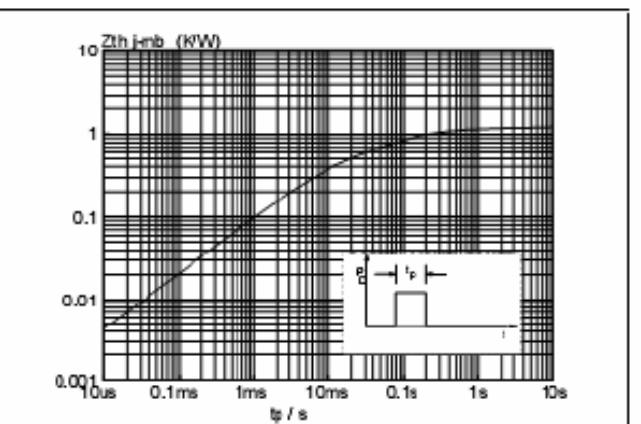


Fig. 11. Transient thermal impedance $Z_{th(j-to-board)}$ versus pulse width t_p .

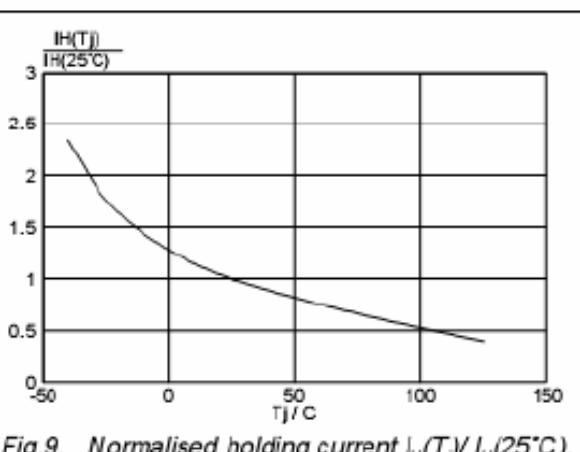


Fig. 9. Normalised holding current $I_H(T_j)/I_H(25^\circ C)$, versus junction temperature T_j

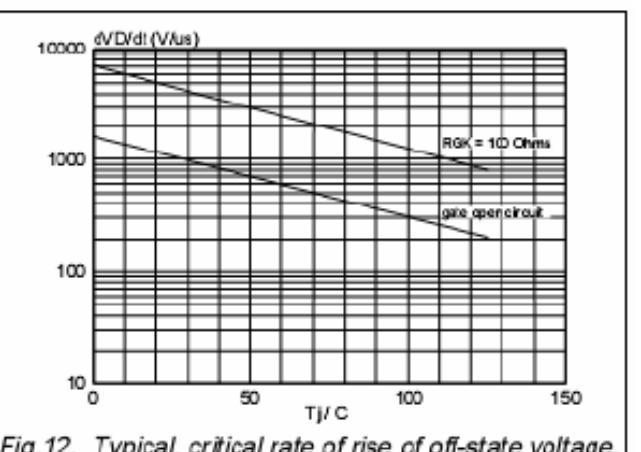


Fig. 12. Typical, critical rate of rise of off-state voltage, dV/dt versus junction temperature T_j .